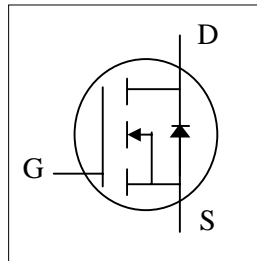




- ▼ Simple Drive Requirement
- ▼ SO-8 Compatible with Heatsink
- ▼ Low On-resistance
- ▼ RoHS Compliant & Halogen-Free

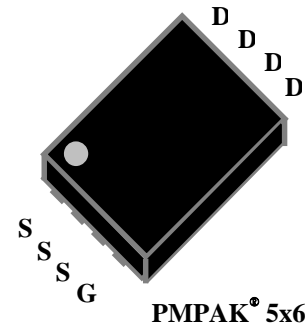


$BV_{DSS}$	30V
$R_{DS(ON)}$	3.1m $\Omega$
$I_D$	100A

## Description

AP9450 series are from Advanced Power innovated design and silicon process technology to achieve the lowest possible on-resistance and fast switching performance. It provides the designer with an extreme efficient device for use in a wide range of power applications.

The PMPAK<sup>®</sup> 5x6 ppackage is special for voltage conversion application using standard infrared reflow technique with the backside heat sink to achieve the good thermal performance.



## Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	30	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D @ T_C = 25^\circ C$	Continuous Drain Current (Chip), $V_{GS} @ 10V^5$	100	A
$I_D @ T_A = 25^\circ C$	Continuous Drain Current <sup>3</sup> , $V_{GS} @ 10V$	32	A
$I_D @ T_A = 70^\circ C$	Continuous Drain Current <sup>3</sup> , $V_{GS} @ 10V$	25.6	A
$I_{DM}$	Pulsed Drain Current <sup>1</sup>	160	A
$P_D @ T_C = 25^\circ C$	Total Power Dissipation	50	W
$P_D @ T_A = 25^\circ C$	Total Power Dissipation	5	W
$E_{AS}$	Single Pulse Avalanche Energy <sup>4</sup>	28.8	mJ
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ C$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ C$

## Thermal Data

Symbol	Parameter	Value	Unit
Rthj-c	Maximum Thermal Resistance, Junction-case	2.5	$^\circ C/W$
Rthj-a	Maximum Thermal Resistance, Junction-ambient <sup>3</sup>	25	$^\circ C/W$



# AP9450GMT-HF

## Electrical Characteristics @T<sub>j</sub>=25°C (unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	30	-	-	V
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V, I <sub>D</sub> =20A	-	2.5	3.1	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =20A	-	4.1	5.4	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250uA	1	1.5	3	V
g <sub>fs</sub>	Forward Transconductance	V <sub>DS</sub> =10V, I <sub>D</sub> =20A	-	65	-	S
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =24V, V <sub>GS</sub> =0V	-	-	10	uA
I <sub>GSS</sub>	Gate-Source Leakage	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	-	-	±100	nA
Q <sub>g</sub>	Total Gate Charge	I <sub>D</sub> =20A	-	30	48	nC
Q <sub>gs</sub>	Gate-Source Charge	V <sub>DS</sub> =15V	-	11	-	nC
Q <sub>gd</sub>	Gate-Drain ("Miller") Charge	V <sub>GS</sub> =4.5V	-	11	-	nC
t <sub>d(on)</sub>	Turn-on Delay Time	V <sub>DS</sub> =15V	-	15	-	ns
t <sub>r</sub>	Rise Time	I <sub>D</sub> =1A	-	11	-	ns
t <sub>d(off)</sub>	Turn-off Delay Time	R <sub>G</sub> =3.3Ω	-	53	-	ns
t <sub>f</sub>	Fall Time	V <sub>GS</sub> =10V	-	36	-	ns
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0V	-	4320	6900	pF
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> =15V	-	600	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	f=1.0MHz	-	36	-	pF
R <sub>g</sub>	Gate Resistance	f=1.0MHz	-	1.3	2.6	Ω

## Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V <sub>SD</sub>	Forward On Voltage <sup>2</sup>	I <sub>S</sub> =20A, V <sub>GS</sub> =0V	-	-	1.2	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>S</sub> =10A, V <sub>GS</sub> =0V,	-	30	-	ns
Q <sub>rr</sub>	Reverse Recovery Charge	di/dt=100A/μs	-	18	-	nC

### Notes:

1. Pulse width limited by Max. junction temperature
2. Pulse test
3. Surface mounted on 1 in<sup>2</sup> copper pad of FR4 board, t ≤ 10sec ; 60°C/W at steady state.
4. Starting T<sub>j</sub>=25°C , V<sub>DD</sub>=30V , L=0.1mH , R<sub>G</sub>=25Ω , I<sub>AS</sub>=24A.
5. Package limitation current is 60A .

THIS PRODUCT IS SENSITIVE TO ELECTROSTATIC DISCHARGE, PLEASE HANDLE WITH CAUTION.

USE OF THIS PRODUCT AS A CRITICAL COMPONENT IN LIFE SUPPORT OR OTHER SIMILAR SYSTEMS IS NOT AUTHORIZED.

APEC DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS.

APEC RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN.

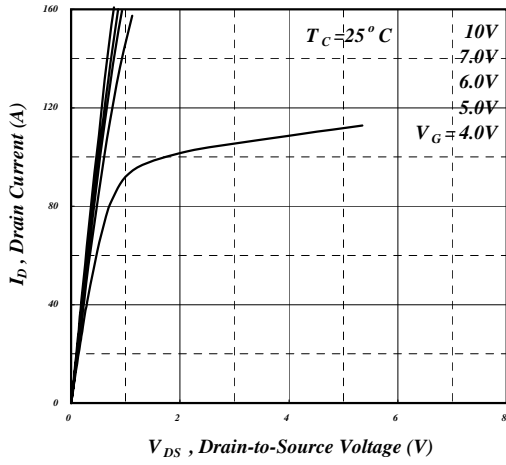


Fig 1. Typical Output Characteristics

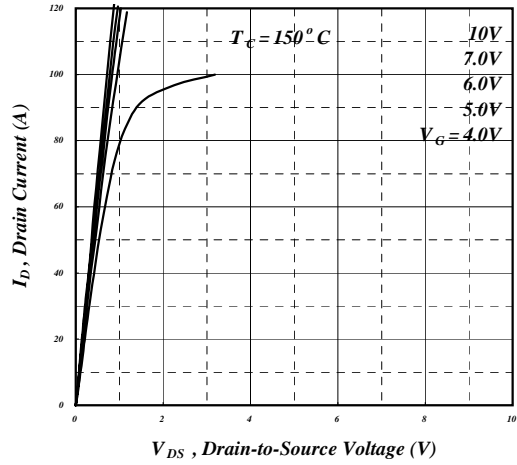


Fig 2. Typical Output Characteristics

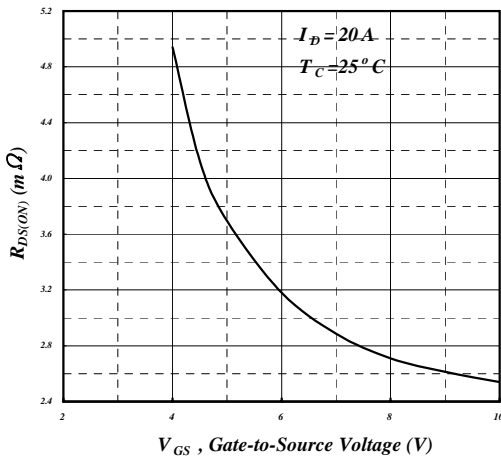


Fig 3. On-Resistance v.s. Gate Voltage

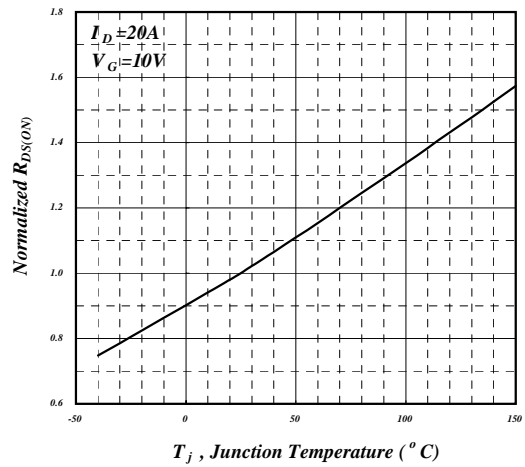


Fig 4. Normalized On-Resistance v.s. Junction Temperature

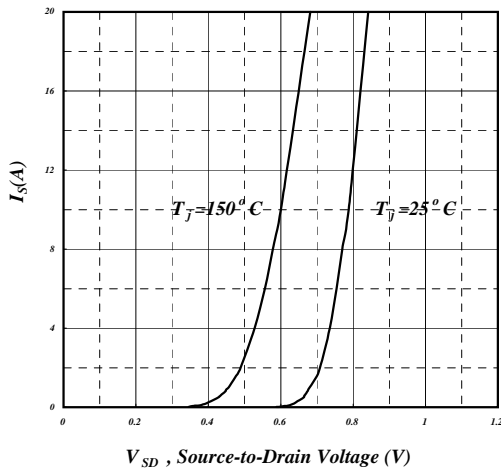


Fig 5. Forward Characteristic of Reverse Diode

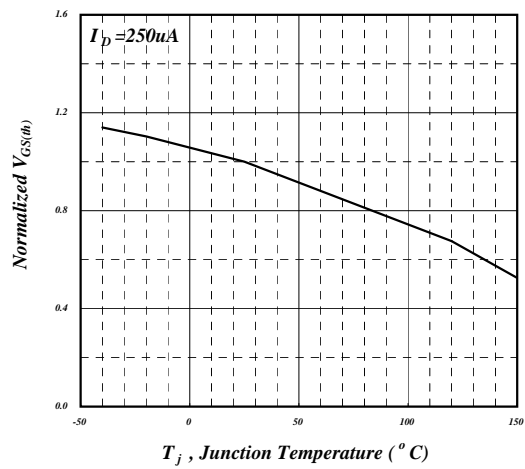


Fig 6. Gate Threshold Voltage v.s. Junction Temperature

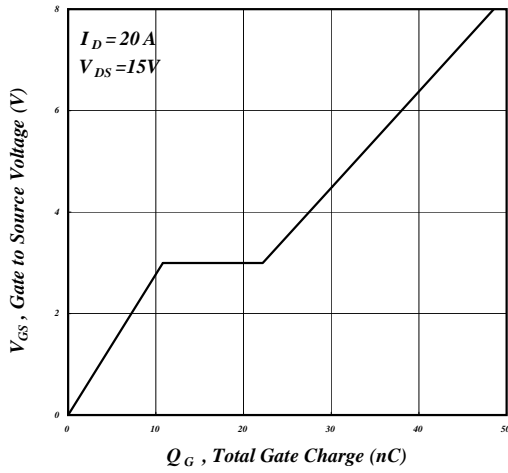


Fig 7. Gate Charge Characteristics

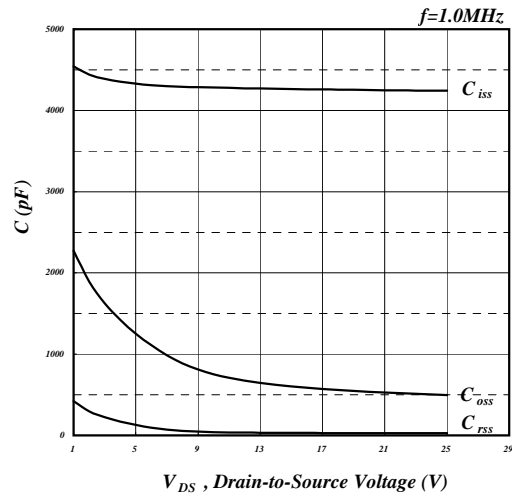


Fig 8. Typical Capacitance Characteristics

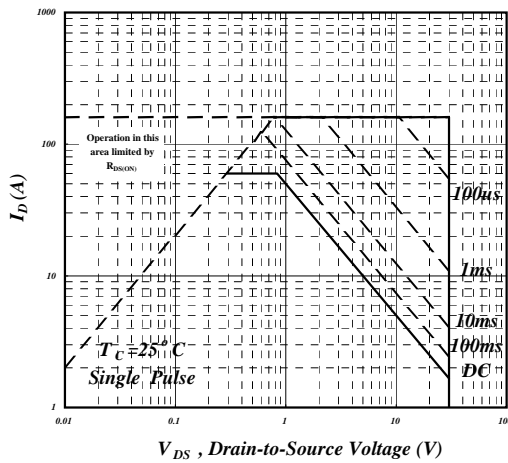


Fig 9. Maximum Safe Operating Area

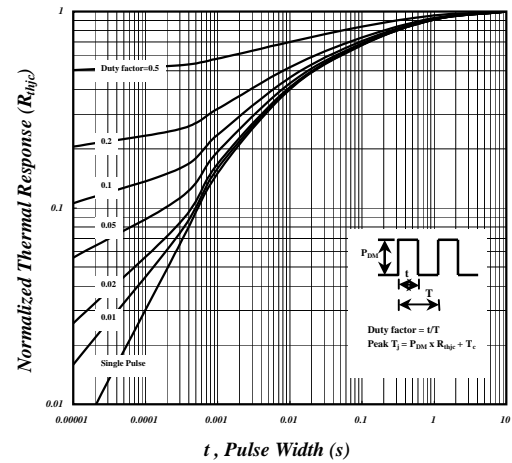


Fig 10. Effective Transient Thermal Impedance

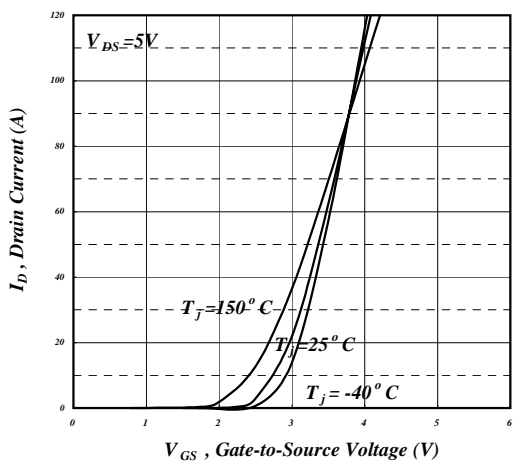


Fig 11. Transfer Characteristics

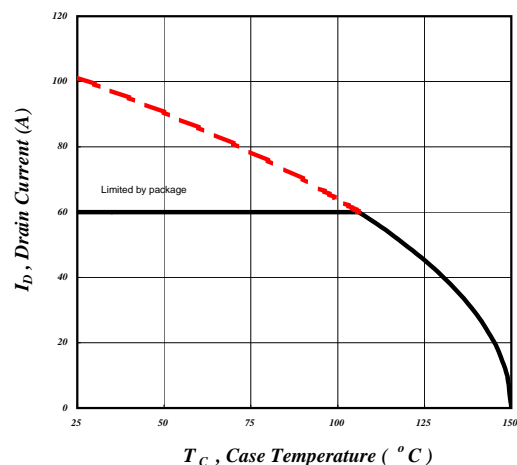


Fig 12. Maximum Continuous Drain Current v.s. Case Temperature